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This listing of claims replaces all prior versions, and listings of claims in the instant application:

Listing of Claims:

1-2. (canceled)

3. (previously presented) A method comprising: coupling a wafer support to a first surface of a substrate;

optically recognizing a first intersection of a first scribe line and a second scribe line coupled to said first surface of said substrate through said wafer support;

aligning a drilling device at said first intersection; and drilling through said substrate at said first intersection with said drilling device from said first surface to a second surface of said substrate to form an alignment mark.

- 4. (currently amended) The method of Claim \pm 3 wherein said wafer support is sufficiently transparent to allow said first intersection to be optically recognized through said wafer support.
- 5. (currently amended) The method of Claim \pm 3 further comprising protecting said first surface of said substrate with said wafer support.
- 6. (previously presented) The method of Claim 5 wherein said drilling generates contaminants, said wafer support protecting said first surface of said substrate from said contaminants.

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7. (currently amended) The method of Claim \pm 3 further comprising aligning a saw with said first scribe line using said alignment mark.

- 8. (previously presented) The method of Claim 7 further comprising shining light at an angle to said second surface of said substrate to enhance recognition of said alignment mark.
- 9. (original) The method of Claim 7 wherein said saw is selected from the group consisting of a mechanical saw, a laser saw, and a high-pressure water saw.
- 10. (original) The method of Claim 7 further comprising cutting said substrate from said second surface with said saw.
- 11. (original) The method of Claim 10 wherein said substrate is cut along said first scribe line.
- 12. (original) The method of Claim 10 wherein said cutting singulates electronic components of said substrate.
- 13. (original) The method of Claim 12 wherein said electronic components are selected from the group consisting of integrated circuits, micromachine chips, and image sensor chips.
 - 14. (original) A method comprising:

coupling a front-side surface of a wafer to an interior surface of a wafer support;

optically recognizing a scribe grid coupled to said frontside surface of said wafer through said wafer support;

aligning a drilling device directly to said scribe grid; and

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drilling through said wafer with said drilling device from said front-side surface to a back-side surface of said wafer to form a back-side alignment mark.

- 15. (original) The method of Claim 14 further comprising protecting said front-side surface of said wafer with said wafer support during said drilling.
- 16. (original) The method of Claim 14 further comprising aligning a saw with said scribe grid using said alignment mark.
- 17. (original) The method of Claim 16 further comprising cutting said wafer from said back-side surface with said saw.
- 18. (original) The method of Claim 17 further comprising protecting said front-side surface of said wafer with said wafer support during said cutting.
- 19. (original) The method of claim 18 further comprising washing said wafer to remove contaminants generated during said cutting.
 - 20. (original) A method comprising:

coupling a front-side surface of a wafer to a wafer support, a first scribe line and a second scribe line being coupled to said front-side surface;

optically recognizing an intersection of said first scribe line and said second scribe line through said wafer support;

aligning a drilling device at said intersection; and drilling through said wafer support and through said wafer at said intersection with said drilling device to form an alignment mark on a back-side surface of said wafer.

21. (original) A method comprising:

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coupling a front-side surface of a wafer to a wafer support, a first scribe line and a second scribe line being coupled to said front-side surface;

optically recognizing an intersection of said first scribe line and said second scribe line through said wafer support;

aligning a drilling device at said intersection;

drilling through said wafer from said front-side surface to a back-side surface of said wafer at said intersection with said drilling device to form an alignment mark on said back-side surface of said wafer;

aligning a saw with said first scribe line using said alignment mark; and

cutting said wafer from said back-side surface with said saw along said first scribe line, wherein said wafer support protects said front-side surface during said cutting.